

## ADT DICING SAWS

ADT's dicing saws' line offer a variety of capabilities, configurations and levels of automation as well as unique solutions for special materials and applications. The dicing saws range includes automatic saws, fully automatic saws with single and double spindle, as well as special machines for tailored applications.



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### ADT'S DICING SAWS UNIQUE FEATURES

#### Advantages

- Low cost of owner ship
- High throughput
- User freindly
- Flexible
- Customization

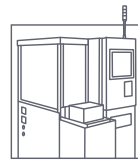
#### Monitoring

- Temperature monitoring
- Water Flow Monitoring
- Kerf Monitoring
- Product mapping - confocal

#### Reliability

- Spindle air reservoir
- UPS – Cut Map Saving
- Broken Blade Detector
- Geometric model finder
- Enhanced Kerf check inspection
- Vibration Dampers
- X Air bearing Axis

### Quality Standards



## Dicing Saws | Fully Automatic

# FULLY AUTOMATIC TWIN SPINDLE DICING SAWS

## 8030

12" Silicon wafer dicing supporting 6" and 8" wafers plus Large QFN multi panels



### Features & Benefits

- Up to 76.2mm (3") Blades OD
- Support up to 12" X 12" chuck
- Ionizer Bar – ESD discharge
- BARCODE item identification
- SECS GEM ready

<b>Workpiece Size</b>	Ø 8", Ø 12" or 12" x 12" square	
<b>Spindle</b>	Two facing 1.8 kW or 2.2 kW, max. 60,000 rpm	
<b>Blade Size</b>	2" – 3"	
<b>Y1 / Y2 Axis</b>	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
<b>X Axis</b>	Resolution	0.2 µm
	Repeatability	1.0 µm
<b>Z1 / Z2 Axis</b>	Max. Stroke	50 mm (for 2.188" blade OD)
	Repeatability	4 arc-sec
<b>Ø Axis</b>	Stroke	380°
	<b>Cleaning Station</b>	Spinning speed
Cleaning Method		Atomized cleaning capabilities
<b>Utilities</b>	Electrical	200-240 VAC, 50/60 Hz, single phase
	<b>Dimensions</b>	(W x D x H) mm
Weight		1,500kg

### Materials:

Silicon wafers | Thin Glass | QFN and BGA multi pannels